# Induced Leakage Currents

M. J. Beck<sup>1,2</sup>, N. Sergueev<sup>1</sup>, <u>Y. S. Puzyrev<sup>1</sup></u>, K. Varga<sup>1</sup>, R. D. Schrimpf<sup>3</sup>, D. M. Fleetwood<sup>3</sup>, S. T. Pantelides<sup>1,3,4</sup>

<sup>1</sup>Dept. of Physics & Astronomy, Vanderbilt University, Nashville, TN 37235 <sup>2</sup>Dept. of Chemical & Materials Engineering, University of Kentucky, Lexington, KY 40506 <sup>3</sup>Dept. of Electrical Engineering & Computer Science, Vanderbilt University, Nashville, TN 37235 <sup>4</sup>Oak Ridge National Laboratory, Oak Ridge, TN

2009 MURI Review

## **Multi-scale calculation**

# From QM transport to I-V device characteristics



# SEGR in SiO<sub>2</sub>

- L =1.4 nm
- Defect energy levels
- Defect atomistic map

time = 78fs 22 defects







# Leakage Current Temperature Dependence





2009 MURI Annual review, Vanderbilt University, June 10 2009

# Direct comparison with experiment



Massengill, et al., IEEE TNS 48 1904 (2001)

## Model results in real-time defect evolution and transient currents





- 3D Mott defect-to-defect calculation of leakage currents
- Low-resistivity paths through oxide layers
- Displacement damage lead to appreciable current

## **Multi-scale calculation**

# From QM transport to I-V device characteristics

